

Amendments to the Claims:

Listing of Claims:

- 1 (original): An extrusion-free wet cleaning process, comprising:
- 5 providing a wet cleaning tool;
- preparing a wafer having a main surface comprising at least one exposed copper feature and a dielectric film;
- transferring said wafer into said wet cleaning tool in a light inhibited manner; and
- cleaning said main surface of said wafer by contacting a cleaning solution in said light
- 10 inhibited manner.
- 2 (original): The extrusion-free wet cleaning process according to claim 1 wherein said wafer is a semiconductor wafer.
- 15 3 (original): The extrusion-free wet cleaning process according to claim 1 wherein said exposed copper feature is damascened into said dielectric film.
- 4 (original): The extrusion-free wet cleaning process according to claim 1 wherein during said cleaning step of said main surface of said wafer in said light inhibited manner, said wafer
- 20 is not exposed to light.

5 (original): The extrusion-free wet cleaning process according to claim 1 wherein said wet cleaning tool comprises a succession of sinks containing said cleaning solution.

6 (original): The extrusion-free wet cleaning process according to claim 1 wherein said
5 wet cleaning tool is a single-wafer cleaning tool.

7 (currently amended): A wafer wet cleaning system comprising a wet cleaning tool for performing a wafer cleaning process, a first light inhibiting means for transferring said wafer into said wet cleaning tool, and a second light inhibiting means for preventing a wafer to be
10 cleaned from light exposure during said wafer cleaning process.

8 (original): The wafer wet cleaning system according to claim 7 wherein said wet cleaning tool comprises a succession of sinks for containing cleaning solution.

15 9 (original): The wafer wet cleaning system according to claim 7 wherein said wet cleaning tool is a single-wafer cleaning tool.

10 (original): The wafer wet cleaning system according to claim 7 wherein said wafer has a main surface comprising at least one exposed copper feature and a dielectric film.

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11 (original): The extrusion free wet cleaning process according to claim 7 wherein said

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wafer is a semiconductor wafer.